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DERWENT-WEEK: 200235

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TITLE: Cooling apparatus for print board assembly

INVENTOR: JU, J H

PATENT-ASSIGNEE: HYNIX SEMICONDUCTOR INC [HYNIN]

PRIORITY-DATA: 1999KR-0060456 (December 22, 1999)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
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KR 2001063385 A	July 9, 2001	N/A
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APPLICATION-DATA:

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INT-CL (IPC): H05K007/20

ABSTRACTED-PUB-NO: KR2001063385A

BASIC-ABSTRACT:

NOVELTY - A cooling apparatus for a print board assembly is provided to enhance the cooling efficiency without using a blow fan in an outdoor system difficult to employ a forced cooling method using the blow fan, thereby saving energy consumption due to the blow fan as well as removing fan noise.

DETAILED DESCRIPTION - The print board assembly(14) having circuit chips(16) is installed on a copper plate(10). A heat pipe(12) connected to the circuit chip(16) is mounted on one side of the copper plate(10), and a heat sink(20) having radiator pins(22) is mounted on the other side of the copper plate(10).

At this time, a flat side of the heat sink(20) is positioned within a rack body(18) and the radiator pins(22) is positioned outside the rack body(18). Therefore, heat generated from the circuit chip(16) is transferred to the copper plate(10) through the heat pipe(12).

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: COOLING APPARATUS PRINT BOARD ASSEMBLE

DERWENT-CLASS: V04 X25

EPI-CODES: V04-Q02A; V04-T03B1; X25-L04;

